

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	35mΩ@10V	25A
	40mΩ@4.5V	

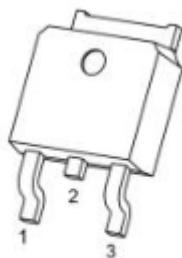
Feature

- $V_{DS} = 100V$, $I_D = 25A$
- $R_{DS(on)} < 50m\Omega$ @ $V_{GS} = 10V$ $R_{DS(on)} < 55m\Omega$ @ $V_{GS} = 4.5V$
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% Single Pulse avalanche energy Test

Application

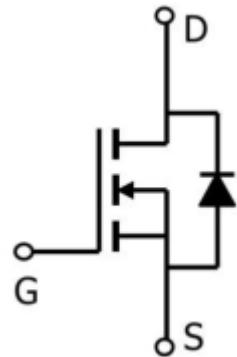
- Power Management Switches
- DC/DC Converter

Package



TO-252(G:1 D:2 S:3)

Circuit diagram



Marking



010N35 : Product code
 ** : Week code.

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_c=25^\circ\text{C}$)	I_D	25	A
Pulsed Drain Current	I_{DM}	100	A
Single Pulse Avalanche Energy ¹	E_{AS}	100	mJ
Total Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	70	W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	1.78	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ\text{C}$

Electrical characteristics

($T_A=25^\circ\text{C}$, unless otherwise noted)

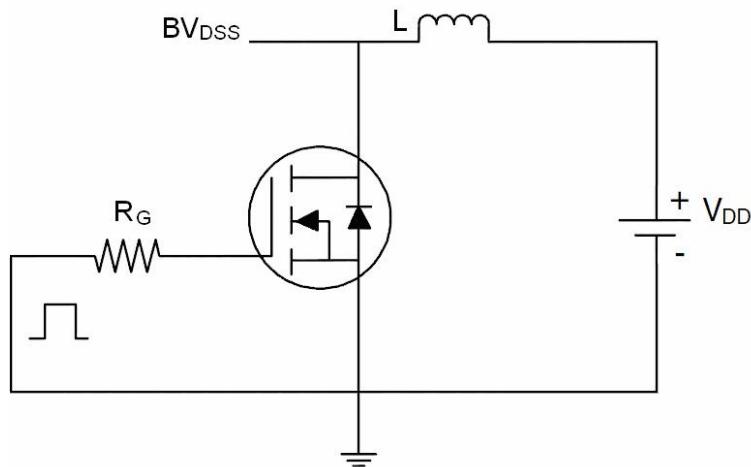
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	μA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	1	1.5	2.5	V
Static Drain-Source on-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 10\text{A}$		35	50	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 6\text{A}$		40	55	
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		3000		pF
Output Capacitance	C_{oss}			96		
Reverse Transfer Capacitance	C_{rss}			55		
Switching Characteristics						
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 50\text{V}, R_{\text{G}} = 3\Omega, I_{\text{D}} = 10\text{A}$		9		nS
Turn-on Rise Time	T_{r}			8		
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$			32		
Turn-Off Fall Time	T_{f}			9		
Total Gate Charge	Q_{g}	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, I_{\text{D}} = 25\text{A}$		70		nC
Gate-Source Charge	Q_{gs}			9		
Gate-Drain Charge	Q_{gd}			18		
Drain-Source Diode Characteristics						
Diode forward voltage	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_{\text{s}} = 1\text{A}$			1.2	V

Notes:

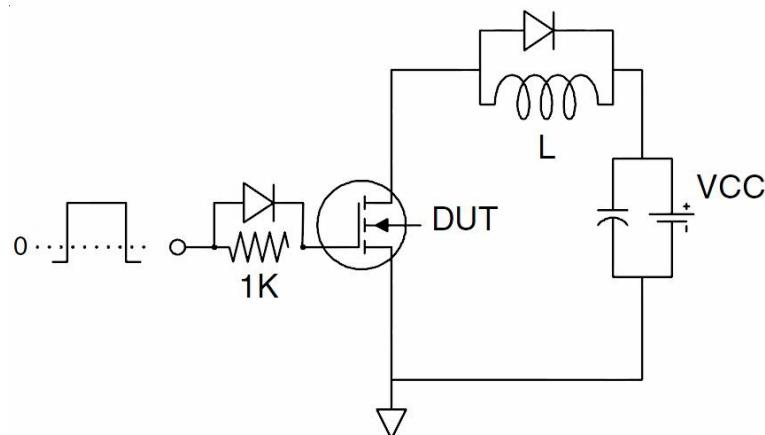
1. EAS condition: $V_{\text{DD}} = 50\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.5\text{mH}, R_{\text{g}} = 25\Omega$

Test Circuit

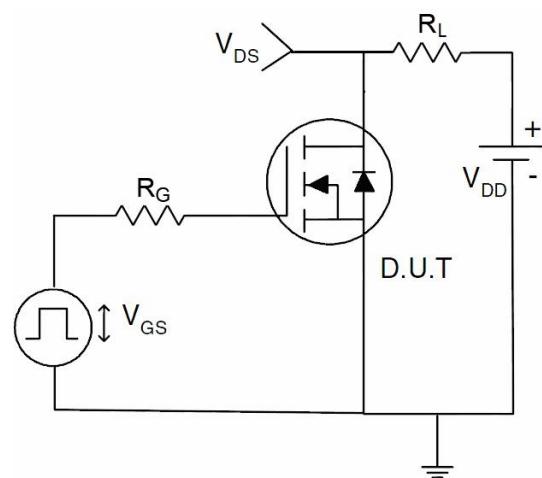
- EAS Test Circuits



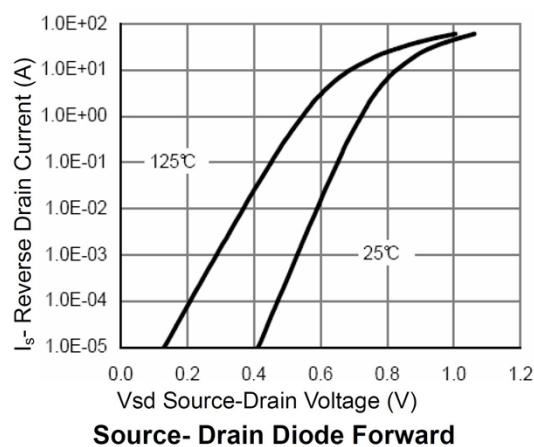
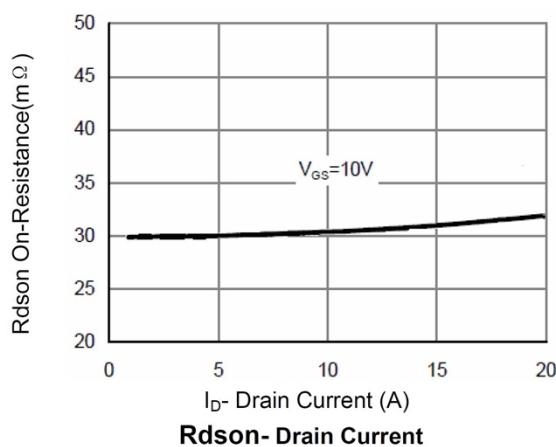
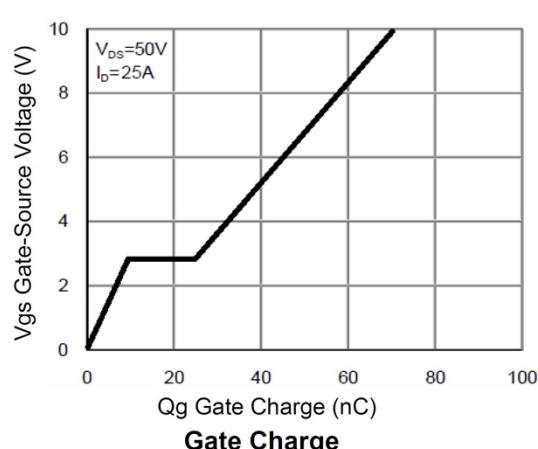
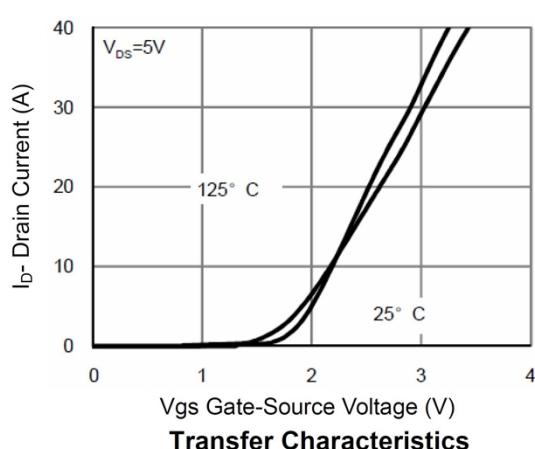
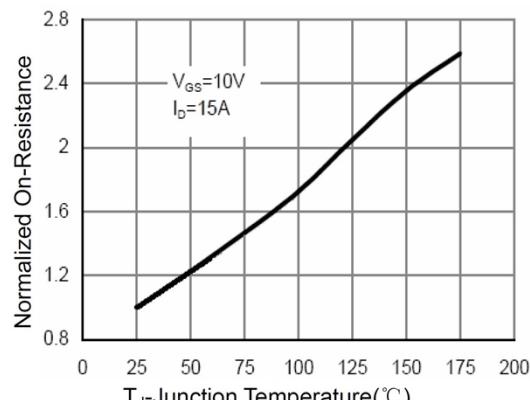
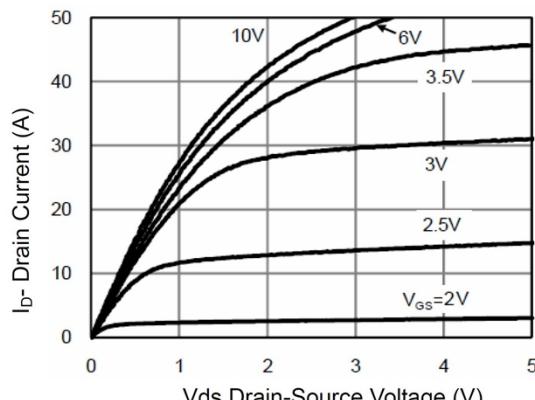
- Gate Charge Test Circuit

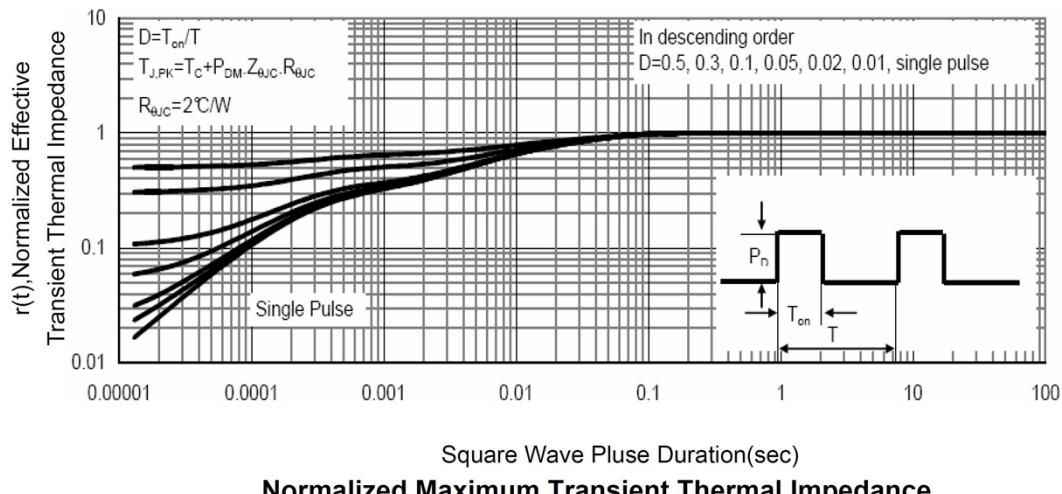
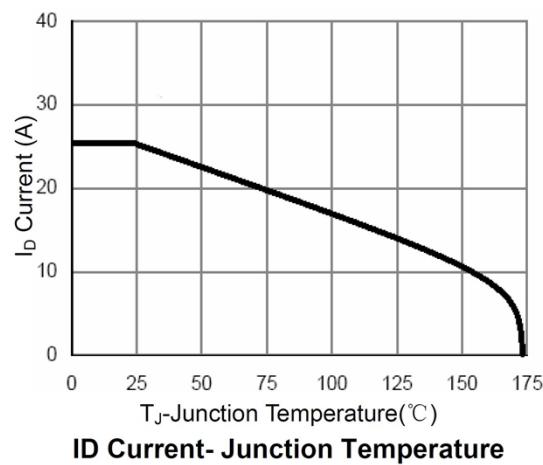
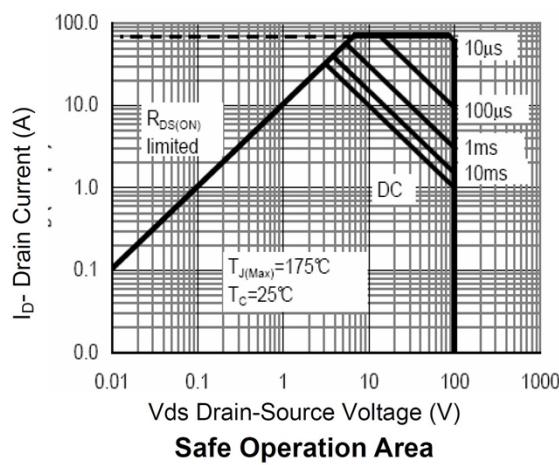
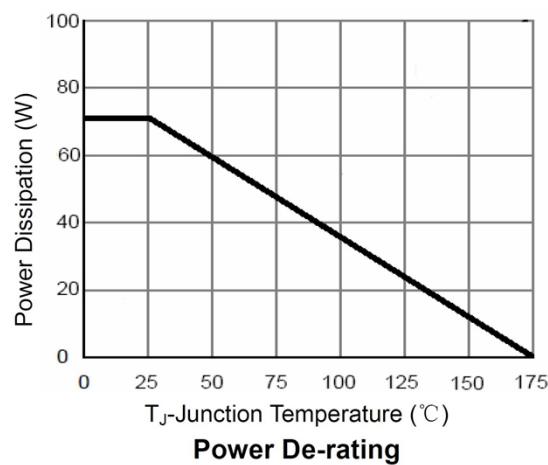
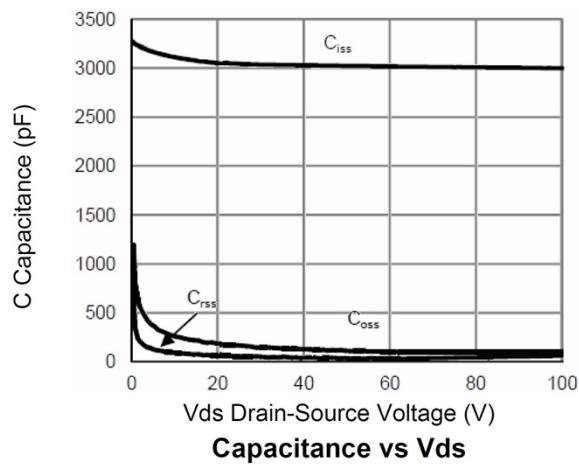


- Switch Time Test Circuit

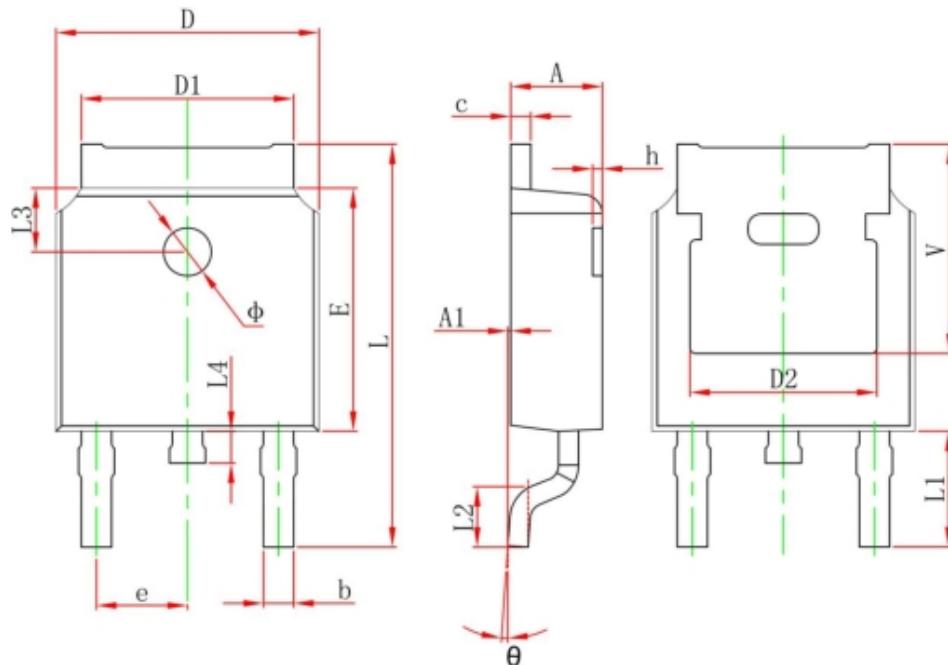


Typical Characteristics





TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	